



Single Chip Microcontroller Plus PLL LSI with On-Chip UVEPROM

Preliminary

Overview

The LC72E32 microcontroller is an on-chip UVEPROM version of the LC7232N single-chip microcontroller plus PLL product. The LC72E32 has the same functions and pin assignment as the LC7232N mask ROM version. Its on-chip EPROM has an 8-Kbyte capacity and a 4-Kword by 16-bit organization. Since programs can be rewritten multiple times, the LC72E32 is optimal for program development.

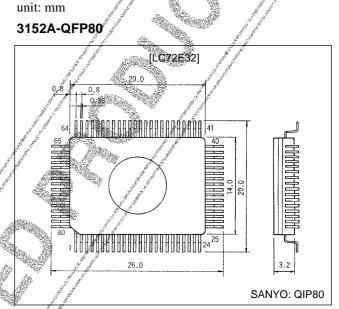
Features

- Options can be switched with EPROM data The LC7232N option functions can be specified with EPROM data. This allows the actual mass production printed circuit board to be used for test product evaluation.
- 8 Kbytes (with a 4-Kword by 16-bit organization) of UVEPROM on chip
 The L C72E22 includes 8 Khetter (SUVEPDOM

The LC72E32 includes 8 Kbytes of UVEPROM (ultraviolet erasable EPROM) on chip

• The pin arrangement is identical to that of the LC7232N mask ROM version, i.e., pin compatibility is maintained.

Package Dimensions



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Specifications

Absolute Maximum Ratings at Ta = 25°C, V_{SS} = 0 V

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	V _{DD} max		-0.3 to +6.5	V
Input voltage	V _{IN} 1	HOLD, INT, RES, ADI, SNS, and the G port $% \mathcal{A} = \mathcal{A} = \mathcal{A}$	+0.3 to +13	V
Input voltage	V _{IN} 2	Inputs other than V _{IN} 1	- → 0 3 to V _{DD} + 0.3	V
Output voltage	V _{OUT} 1	H port	–0.3 to +15	V
Output voltage	V _{OUT} 2	Outputs other than V _{OUT} 1	–0.3 to ¥ _{DD} + 0.3	/ v
	I _{OUT} 1	All D and H port pins	0 to 5	mA
Output current	I _{OUT} 2	All E and F port pins	0 to 3	mA
Output current	I _{OUT} 3	All B and C port pins	0 to 1	mA
	I _{OUT} 4	S1 to S28 and all I port pins	0 to 1	mA
Allowable power dissipation	Pd max	Topg = 10 to 40°C	400	mW
Operating temperature	Topr		10 to 40	°C
Storage temperature	Tstg			°C

Note: There are circuits in this IC with reduced resistance to damage from static electricity. Thus speelar care is required when handling this product. Allowable Operating Ranges at Ta = 10 to 40° C, V_{DD} = 3.5 to 5.5 V

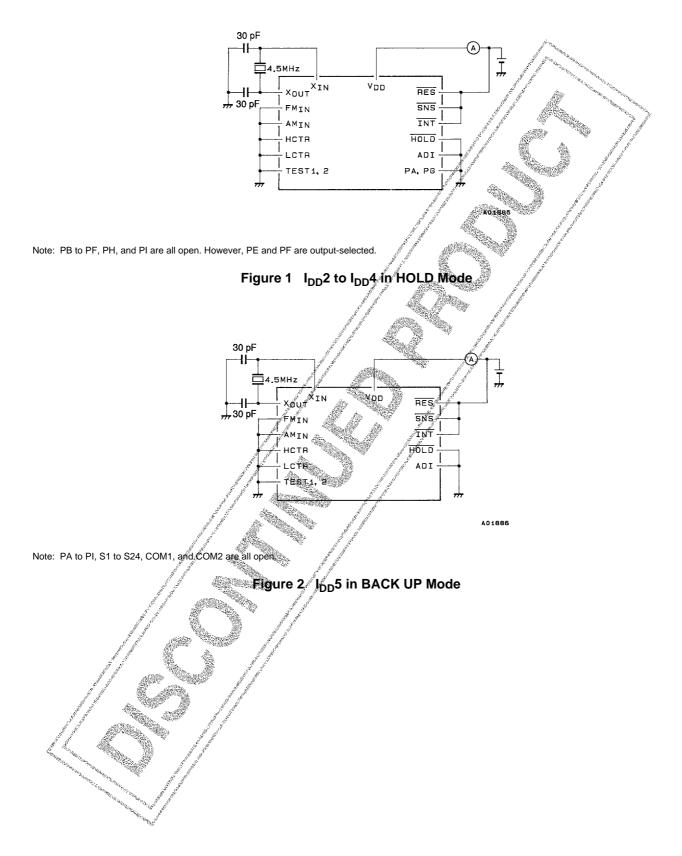
Allowable Operating Ranges at Ta = 10 to 40°C, V_{DD} = 3.5 to 5.5 V

			^{pr} pr		
Symbol	Conditions		, u	70 0 1	Unit
V 4		<u> </u>	тур	-	V
		4 4			V V
		1 A A		-	V V
					V V
		0.7 V _{DD}	0.0		V
	2 8 22 2 2000 200 21 1		8.0	•	V
					-
					V
2					V
2 2					V
5 15		-			V
		-			V
	. Walay 60.00	-		-	V
					V
V _{IL} 5		0		0.3 V _{DD}	V
VILG	LCTR (period measurement), V _{DD} 1	0		0.2 V _{DD}	V
VnZ	HQLD	0		0.4 V _{DD}	V
f _{IN} tes	XIN	4.0	4.5	5.0	MHz
f _{1N} 2	FMIN, V _{IN} 2, V _{DD} 1	10		130	MHz
f _{IN} 3	FMIN, V _{IN} 3, V _{DD} 1	10		150	MHz
t _{IN} 4	AMIN (L), V _{IN} 4, V _{DD} 1	0.5		10	MHz
🔬 f _{IN} 5 🍃	AMIN (H), V _{IN} 5, V _{DD} 1	2.0		40	MHz
f _{IN} 6	HCTR, V _{IN} 6, V _{DD} 1	0.4		12	MHz
f _{IN} 7	LCTR (frequency), V _{IN} 7, V _{DD} 1	100		500	kHz
₩N8	LCTR (period), V _{IH} 6, V _{IL} 6, V _{DD} 1	1		$20 imes 10^3$	Hz
V _{IN} 1	XIN	0.50		1.5	Vrms
V _{IN} 2	FMIN	0.10		1.5	Vrms
۶ V _{IN} 3	FMIN	0.15		1.5	Vrms
V _{IN} 4, 5	AMIN	0.10		1.5	Vrms
V _{IN} 6, 7	LCTR, HCTR	0.10		1.5	Vrms
		I			1
	V _{DD} 1 V _{DD} 2 V _{DD} 3 V _{IH} 1 V _{IH} 2 V _{IH} 3 V _{IH} 4 V _{IH} 5 V _{IL} 6 V _{IL} 7 V _{IL} 8 V _{IL} 9 V _{IL} 1 V _{IL} 2 V _{IL} 3 V _{IL} 4 V _{IL} 5 V _{IL} 6 V _{IL} 7 f _{IN} 7 f _{IN} 8 f _{IN} 8 V _{IN} 1 V _{IN} 2 V _{IN} 3 V _{IN} 4, 5	$\label{eq:second} \begin{array}{ c c c c c } \hline V_{DD}1 & CPU and PLL operating \\ \hline V_{DD}2 & CPU operating \\ \hline V_{DD}3 & Memory retention voltage \\ \hline V_{IH}1 & G port \\ \hline V_{IH}2 & RES, IMT, flotD 0.8, V_{DD} \\ \hline V_{IH}3 & SNS \\ \hline V_{IH}4 & A port \\ \hline V_{IH5} & E and F ports \\ \hline V_{IH6} & LCTR (period measurement), V_{DB}1 \\ \hline V_{IL6} & LCTR (period measurement), V_{DB}1 \\ \hline V_{IL7} & G port \\ \hline V_{IL2} & RES, IMT \\ \hline V_{IL6} & LCTR (period measurement), V_{DB}1 \\ \hline V_{IL7} & G port \\ \hline V_{IL6} & E and F ports \\ \hline V_{IL6} & LCTR (period measurement), V_{DD}1 \\ \hline V_{IL7} & RES, IMT \\ \hline V_{IL6} & LCTR (period measurement), V_{DD}1 \\ \hline V_{IL7} & HQLD \\ \hline f_{IN1} & XIN \\ \hline f_{IN2} & FMIN, V_{IN2}, V_{DD}1 \\ \hline f_{IN2} & FMIN, V_{IN3}, V_{DD}1 \\ \hline f_{IN3} & FMIN, V_{IN3}, V_{DD}1 \\ \hline f_{IN5} & AMIN (H), V_{IN5}, V_{DD}1 \\ \hline f_{IN6} & HCTR, V_{IN6}, V_{DD}1 \\ \hline f_{IN7} & LCTR (period), V_{IH6}, V_{IL6}, V_{DD}1 \\ \hline f_{IN8} & LCTR (period), V_{IH6}, V_{IL6}, V_{DD}1 \\ \hline f_{IN8} & LCTR (period), V_{IH6}, V_{IL6}, V_{DD}1 \\ \hline f_{IN6} & HCTR, V_{IN6}, V_{DD}1 \\ \hline f_{IN7} & LCTR (period), V_{IH6}, V_{IL6}, V_{DD}1 \\ \hline f_{IN8} & LCTR (period), V_{IH6}, V_{IL6}, V_{DD}1 \\ \hline f_{IN8} & LCTR (period), V_{IH6}, V_{IL6}, V_{DD}1 \\ \hline f_{IN8} & LCTR (period), V_{IH6}, V_{IL6}, V_{DD}1 \\ \hline f_{IN8} & LCTR (period), V_{IH6}, V_{IL6}, V_{DD}1 \\ \hline f_{IN8} & FMIN \\ \hline V_{IN1} & XIN \\ \hline V_{IN1} & XIN \\ \hline V_{IN2} & FMIN \\ \hline V_{IN3} & FMIN \\ \hline V_{IN4} & 5 & AMIN \\ \hline \end{array}$	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	min typ V _{DD} 1 CPU and PLL operating 4.5; V _{DD} 2 CPU operating 3.5 V _{DD} 3 Memory retention voltage 1.3 V _{IH} 1 G port 6.7 V _{DD} V _{IH} 2 RES, IMT, #OLD 0.8 V _{DD} 3 8.0 V _{IH} 3 SNS 2.5 V _{IH} 4 Aport 0.6 V _{DD} V _{IH} 5 E, and F ports 0.7 V _{DD} V _{IL} 6 /LCTR (petiod measurement), V _{DD} 1 0.8 V _{DD} V _{IL} 3 SNS 0 V _{IL} 4 A port 0 V _{IL} 5 E, and F ports 0 V _{IL} 6 LCTR (petiod measurement), V _{DD} 1 0 V _{IL} 6 LCTR (period measurement), V _{DD} 1 0 V _{IL} 6 LCTR (period measurement), V _{DD} 1 0 V _{IL} 6 LCTR (period measurement), V _{DD} 1 0 V _{IL} 7 HQLD 0 0 V _{IL} 8 FMIN, V _{IN} 2, V _{DD} 1 10 1 f _{IN} 7 HQLD 0 0 1	Symbol Conditions min typ max V _{DD} 1 CPU and PLL operating 4.5 5.5 V _{DD} 2 CPU operating 3.5 5.5 V _{DD} 3 Memory retention voltage 1.3 5.5 V _{IH} 1 G port 0.7 V _{DD} 8.0 V _{IH} 2 RES, TM, BOLD 0.8 V _{DD} 8.0 V V _{H4} 3 SN 2.5 8.0 V _{H4} 4 Aport 0.6 V _{DD} V _{DD} V _{H5} E, and F ports 0.7 V _{DD} V _{DD} V _{H6} // CTR (period measurement), V _{D0} 1 0.8 V _{DD} V _{DD} V _{H6} // CTR (period measurement), V _{D0} 1 0.8 V _{DD} V _{DD} V _{H4} 3 SNS 0 1.3 V _{H6} // CTR (period measurement), V _{D0} 1 0.8 V _{DD} V _{DD} V _{H2} 4 A port 0 0.2 V _{DD} V _{H2} 5 E and F ports 0 0.2 V _{DD} V _{H2} 6 LCTR (period measurement), V _{DD} 1 0 0.4 V _{DD} V _{H2} 6 LC

Electrical Characteristics for the Allowable Operating Ranges

Deversation	Queeb al	Conditions		Ratings		11 14
Parameter	Symbol	Conditions	min	typ	max	Unit
Hysteresis	V _H	LCTR (period), RES, INT	0.1 V _{DD}		5	V
Rejected pulse width	P _{REJ}	SNS			50	μs
Power-down detection voltage	V _{DET}		3.0	3.5	4.0	V
	I _{IH} 1	INT, HOLD, RES, ADI, SNS, and G port: V _I = 5.5 V	and the second second	1 65	3.0	μA
	I _{IH} 2	A, E, and F ports: E and F ports with outputs off, A port with no R_{PD} , $V_I = V_{DD}$			3.0	μA
Input high level current	I _{IH} 3	XIN: $V_{I} = V_{DD} = 5.0 V$	2.0	5.0	a rd 1 5	μA
	I _{IH} 4	FMIN, AMIN, HCTR, LCTR: $V_I = V_{DD} = 5.0 V$	4.0	10	30	μA
	I _{IH} 5	A port: With an R_{PD} , $V_I = V_{DD} = 5.0 V$	1	50	and all all and a second s	μA
	I _{IL} 1	INT, HOLD, RES, ADI, SNS, and G port: $V_I = V_{SS}$			3.0	μA
Input low level current	I _{IL} 2	A, E, and F ports: E and F ports with outputs off, A port with no $R_{PD_s} V_L = V_{SS}$		and the second sec	3.0	μA
	I _{IL} 3	XIN: V _{IN} = V _{SS}	2.0	5.0	15	μA
	I _{IL} 4	FMIN, AMIN, HCTR, LCTR: $V_{I} = V_{SS}$	4.0	10	30	μA
Input floating voltage	V _{IF}	A port: With an R _{PD}		J.	0.05 V _{DD}	V
Pull-down resistance	R _{PD}	A port: With an $R_{PD} = 5.0 V$	75	100	200	kΩ
	I _{OFFH} 1	EO1, EO2: V _O = V _{DD}		0.01	10	nA
Output high level off leakage current	I _{OFFH} 2	B, C, D, E, F, and I ports: $V_0 = V_{DD}$	and the second s		3.0	μA
	I _{OFFH} 3	H port: V _O = 13 V	and a start		5.0	μA
Output low level off leakage current	I _{OFFL} 1	EO1, EO2: V _O = V _{SS}		0.01	10	nA
	I _{OFFL} 2	B, C, D/E, F, and ports: $V_{O} = V_{DD}$	Ĵ.		3.0	μΑ
	V _{OH} 1	B and C ports: Io = 1 mA	V _{DD} – 2.0	V _{DD} – 1.0	V _{DD} – 0.5	V
	V _{OH} 2	E and F ports: IO = 1 mA	V _{DD} - 1.0			V
Output high lovel veltage	V _{OH} 3	/ΕΘ1, ΕΟ2: Ι _Ο	V _{DD} - 1.0			V V
Output high level voltage	V _{OH} 4	S1 to S28 and I port: $I_0 = -0.1 \text{ mA}$	V _{DD} - 1.0			V
	V _{OH} 5	D port $l_0 = 5 \text{ mA}$	V _{DD} – 1.0			V V
	VØH9 V _{ØH} 7	COM1 and COM2: I _O <i>=</i> 25 μA	V _{DD} - 1.0 V _{DD} - 0.75	V _{DD} – 0.5	V _{DD} – 0.3	V
	V _{OL} 1	B and C ports: I _O = 50 µA	0.5	1.0	v _{DD} = 0.3 2.0	V
Marine and a second	V _{OL} 2	E and F ports: $I_0 = 1^{\circ}$ mA	0.0	1.0	1.0	V
a de la companya de l	V _{OL} 3	EO1, EO2: Ι _{Ο,} # 500 μΑ			1.0	V
	Vol4	XQUT: Ι _O = 200 μA			1.0	V
Output low level voltage	Völ5	S1 to S28 and I port: I _O = 0.1 mA			1.0	V
	V _{OL} 6	D port: 1 ₀ = 5 mA			1.0	V
	V _{OL} 7	COM1, COM2: I _O = 25 µA	0.3	0.5	0.75	V
I save	V _{OL} 8	H port: I _O = 5 mA	(150 Ω) 0.75		(400 Ω) 2.0	V
Output middle level voltage	V _M 1	COM1, COM2: V _{DD} = 5.0 V, I _O = 20 μA	2.0	2.5	3.0	V
A/D conversion error		ADI: V _{DD} 1	-1/2		1/2	LSB
T & ABSA.	I _{DD} 1	V _{DD} 1, f _{IN} 2 = 130 MHz		15	20	mA
- // <u>N</u>	IDD2	V _{DD} = 5.0 V, PLL stopped, CT = 2.67 μs (HOLD mode, Figure 1)		2.7		mA
1/2000	Jack Indiana Indiana	V_{DD} = 5.0 V, PLL stopped, CT = 13.33 µs (HOLD mode, Figure 1)		1.7		mA
Current drain	I _{DD} 4	V_{DD} = 5.0 V, PLL stopped, CT = 40.00 μs (HOLD mode, Figure 1)		1.5		mA
~~//	I _{DD} 5	V _{DD} = 5.5 V, oscillator stopped, Ta = 25°C (BACK UP mode, Figure 2)			5	μA
	רסטי	V_{DD} = 2.5 V, oscillator stopped, Ta = 25°C (BACK UP mode, Figure 2)			1	μA

Test Circuits



Pin Functions

Pin	Pin No.	Function	I/O	I/O circuit type	EPROM mode function
PA0 PA1 PA2 PA3	35 34 33 32	Low threshold type dedicated input port These pins can be used, for example, for key data acquisition. Built-in pull-down resistors can be specified as an option. This option is in 4-pin units, and cannot be specified for individual pins. Input through these pins is disabled in BACKUP mode.	Input	BACK UP P P P P P P P P P P P P P	
PB0	30		J.S.	1 - March Margar	and the second sec
PB1	29	Dedicated output ports	فتعجره ومعجور		
PB2	28	Since the output transistor impedances are unbalanced		Constant II	
PB3	27	CMOS, these pins can be effectively used for functions such			
PC0	26	as key scan timing. These pins go to the output high impedance state in BACKUP mode.	and the second	Na. N. //	
PC1	25	These pins go to the low level during a reset, i.e., when the	ji de Ma	6 9 J	
PC2	24	RES pin is low.			
PC3	23	· · · · · · · · · · · · · · · · · · ·	Output		
		and the second sec			
		Dedicated output port	19 (s. 67 - 6	BACK UP	
PD0	22	These are normal CMOS outputs. These pins go to the output			
PD1	21	high impedance state in BACKUP mode.		A01888	
PD2	20	These pins go to the low level during a reset, i.e., when the			
PD3	19	RES pin is low.	nage.		
		<u> </u>	Start of	ŕ	
PE0 PE1 PE2 PE3 PF0 PF1 PF2 PF3	18 17 16 15 14 13 12 11 10 10 10 10 10 10 10 10 10 10 10 10	 I/O port These pins are switched between input and output as follows. Once an input instruction (IN, TPT, or TPF) is executed, these pins latch in the input mode. Once an output instruction (OUT, SPB, or RPB) is executed, they latch in the output mode. These pins go to the input mode during a reset, i.e., when the RES pin is low. In BACKUP mode these pins go to the input mode with input disabled. I/O port These pins are switched between input and output by the FPC instruction. The I/O states of this port can be specified for individual pins. These pins go to the input mode during a reset, i.e., when the RES pin is low. In BACKUP mode these pins go to the input and output by the FPC instruction. The I/O states of this port can be specified for individual pins. These pins go to the input mode during a reset, i.e., when the RES pin is forw. In BACKUP mode these pins go to the input mode with input disabled. 	We want and a second seco	BACK UP	Data I/O PE0: D0 PE1: D1 PE2: D2 PE3: D3 PF0: D4 PF1: D5 PF2: D6 PF3: D7
PG0 PG1 PG2 PG3	4 3	Dedicated input port Input through these pins is disabled in BACKUP mode.	Input	BACK UP EPROM mode A01890	EPROM contro signal inputs PG0: CE PG1: OE

Pin	Pin No.	Function	I/O	I/O circuit type	EPROM mode function
PH0 PH1 PH2 PH3	10 9 8 7	Dedicated output port Since these pins are high breakdown voltage n-channel transistor open-drain outputs, they can be effectively used for functions such as band power supply switching. Note that PH2 and PH3 also function as the DAC1 and DAC2 outputs. These pins go to the high impedance state during a reset, i.e., when the RES pin is low, and in BACKUP mode.	Output	BACK UP	
PI0/S25 PI1/S26 PI2/S27 PI3/S28	39 38 37 36	Dedicated output port While these pins have a CMOS output circuit structure, they can be switched to function as LCD drivers. Their function is switched by the SS and RS instructions. These pins cannot be switched individually. The LCD driver function is selected and a segment off signal is output when power is first applied or when RES is low. These pins are held at the low level in BACKUP mode. Note that when the general-purpose port use option is specified, these pins output the contents of IPORT when LRC is 1, and the contents of the general-purpose output port LATCH when LPC is 0.	ούφι	LCD output I port	
S1 to S14	63 to 50	LCD driver segment outputs A frame frequency of 100 Hz and a 1/2 duty, 1/2 bias drive type are used.	and the second s	EPROM mode BACK UP	Address input S1: A0 to S14: A13
S15 to S24	49 to 40	A segment off signal is output when power is first applied or when RES is low. These pins are held at the low level in BACKUP mode. The use of these pins as general-purpose output ports can be specified as an option.	Output	BACK UP	
COM1 COM2	65 ment	LCD driver common outputs A 1/2 duty, 1/2 bias drive type is used. The output when power is first applied or when RES is low is identical to the normal operating mode output. These pins are held at the low level in BACKUP mode.	Output	BACK UP A01895	
EMIN	75	FM VCO (local oscillator) input The input must be capacitor-coupled. The input frequency range is from 10 to 130 MHz. AM VCO (local oscillator) input The band supported by this pin can be selected using the PLL instruction. High (2 to 40 MHz) \rightarrow SW	Input	HOLD or PLL STOP instruction	

Pin	Pin No.	Function	I/O	I/O circuit type	EPROM mode function
HCTR	70	Universal counter input The input should be capacitor-coupled. The input frequency range is from 0.4 to 12 MHz. This input can be effectively used for FM IF or AM IF counting.			And the second sec
LCTR	71	Universal counter input The input should be capacitor-coupled for input frequencies in the range 100 to 150 kHz. Capacitor coupling is not required for input frequencies from 1 to 20 Hz. This input can be effectively used for AM IF counting.	Input	HOLD or PLL STOP instruction	and a set of the set o
ADI	69	A/D converter input A 1.28 ms period is required for a 6-bit sequential comparison conversion. The full scale input is ((63/96) · V _{DD}) for a data value of 3FH.	Input	ref HOLD or PLL STOP instruction ## A01898	
INT	66	Interrupt request input An interrupt is generated when the INTEN flag is set (by an SS instruction) and a falling edge is input.	Input	A01899	
EO1 EO2	77 78	Reference frequency and programmable divisor phase comparison error outputs Charge pump circuits are built in. EO1 and EO2 are the same	Output	A01900	
SNS	72	Input pin used to determine if a power outage has occurred in BACKUP mode This pin can also be used as a normal input port.	Input	401901	
HOLD	67	Input pin used to force the LC72E32 to HQLD mode The LC72E32 goes to HQLD mode when the HOLDEN flag is set (by an SS instruction) and the HOLD input goes low. A high breakdown voltage circuit is used so that this input can be used in conjunction with the normal power switch.	Input	A01901	
RES	44468 468	System reset input Trus signal should be held low for 75 ms after power is first applied to effect a power-up reset. The reset starts when a low level has been input for at least six reference clock cycles.	Input	A01899	
XIN XOUT	1	Crystal oscillator connections (4.5 MHz)	Input Output		
	Series Street	A feedback resistor is built in.		XDUT 0	
TEST1 TEST2	79 2	LSI test pins. These pins must be connected to $V_{\text{SS}}.$			
V _{DD}	31, 73	Power supply + connections. Both pins must be connected.			EPROM write power Vpp
V _{SS}	76	Power supply – connection.			

Option

No.	Description	Selections	
1	WDT (watchdog timer) inclusion selection	WDT included	
1	WD1 (watchdog timer) inclusion selection	No WDT	
2	Port A pull-down resistor inclusion selection	Pull-down resistors included	
2	For A pull-down resistor inclusion selection	No pull-down resistors	
		2.67 µs	
3	Cycle time selection	13.33 µs]// 《��、 >7
		40.00 µs	21 @ 11
4	LCD port/general-purpose port selection	LCD ports	7 - 4 - 1/
4		General-purpose output ports] & % and //

Usage Notes

The LC72E32 is provided for development of LC7232N application programs and for LC7232N function evaluation. The points listed below required attention when using the LC72E32

1. Differences between the LC72E32 and the LC7232N

Item		LC72E32	LC7232N
Operating temperate	ure (Topr)	10 to 40 °C	_40 to +85°€
Operation immediat following power on	ely	After the 75 ms power on reset period/ the LSI internal option settings are set up during a period of about 1 ms. After that operation completes, program execution starts with the program counter set to location 0	After the 76 ms power on reset period, program execution starts with the program counter set to location 0.
Input type of the A p immediately followin		No pull-down resistors	Pull-down resistors are included or not according to the option specifications.
Output type of the S outputs immediately power on*		LCD ports	These pins function as either LCD ports or general- purpose output ports according to the option specifications.
Power-down detecti (V _{DET})	on voltage	Minimum: 3.0 V Typical: 3.5 V Maximum; 4.9 V	Minimum: 2.7 V Typical: 3.0 V Maximum: 3.3 V
	I _{DD} 2	Conditions: V _{DD} = 5.0 V; PLL stopped CT ⇒ 2.67 µs (HQLD mode, Figure 1) Typical: 2.7 mA	Conditions: V _{DD} 2, PLL stopped CT = 2.67 µs (HOLD mode, Figure 1) Typical: 1.5 mA
Current drain	I _{DD} 3	Conditions: V _{DD} = 5.0 V, PLL stopped GT = 13.33 μs (HOLD mode, Figure 1) Typical: 1.7 mA	$\begin{array}{c} \mbox{Conditions: } V_{DD}2, \mbox{PLL stopped} \\ \mbox{CT} = 13.33 \ \mbox{\mu s} \ (\mbox{HOLD mode, Figure 1}) \\ \mbox{Typical: } 1.0 \ \mbox{mA} \end{array}$
	I _{DD} 4	Conditions: V _{DD} = 5:0 V, PLL stopped C∓ = 40.00 µs (HOLD mode, Figure 1) Typical: 1.5 mA	$\begin{array}{c} \mbox{Conditions: } V_{DD}2, \mbox{PLL stopped} \\ \mbox{CT} = 40.00 \ \mbox{\mu s} \ (\mbox{HOLD mode, Figure 1}) \\ \mbox{Typical: } 0.7 \ \mbox{mA} \end{array}$
The TEST1 and TE	ST2 pins	These are tSI test pins and must be connected to $V_{SS}.$	These are LSI test pins and must be either left open or connected to $V_{\text{SS}}.$

Note: * This refers to the option setup time of about 1, ms that occurs following the period of about 75 ms from power application.

2. PLA and options

The LC72E32 uses location 2000H to 201FH as program memory for PLA pattern specification, and locations 2020H to 2033H for option specification. This option specification allows the LC72E32 to support option setups identical to those available with the LC7232N.

LC72E32 Option Types

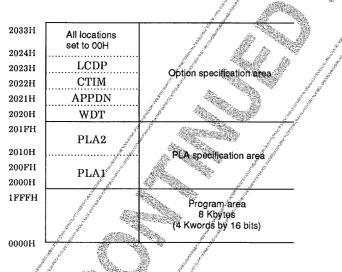
Symbol	Option Type	Selections	
WDT	WDT (watchdog timer) inclusion coloction	WDT included	
VVDT	WDT (watchdog timer) inclusion selection	No WDT	
APPDN	A part pull down register inclusion extertion	Pull-down resistors included	
AFFDN	A port pull-down resistor inclusion selection	No pull-down resistors	
		2.67 µs	
СТІМ	Cycle time selection	13.33 µs]// 《�� >
		40.00 µs]/ 🔊 ∿ //
LCDP	LCD port/general-purpose port selection	LCD ports] 🕷 🐁 //
	COD porregeneral-purpose porr selection	General-purpose output ports	

Note that these options are not determined until the option setting period of about 1 ans, which follows a period of about 75 ms from power application, has passed.

3. Use of the mass produced unit printed circuit board

When using the printed circuit board for the massed produced end product with the LC72E32, be sure to connect the TEST1 and TEST2 pins to V_{SS} and be sure to connect both pins 31 and 73 (the V_{DD} pins) to the plus side of the power supply.

4. EPROM address space



Note: Due to their structure, on-chip EPROM microcontrollers (products in which the EPROM has not been written) cannot be fully tested prior to shipment. As a result, the yield after writing may be decreased.



Usage Techniques

1. Writing the on-chip EPROM

There are two techniques that can be used to write to the LC72E32's on-chip EPROM.

• Use of a general-purpose EPROM programmer

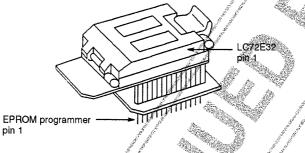
The LC72E32's EPROM can be written using a general-purpose EPROM programmer. This requires the use of a special-purpose adapter, the LC72E32 Adapter for EPROM Programmer. Use the Intel 27512 ($Vpp \neq 12.5 V$) high-speed writing technique, and specify the address settings as locations 0 to 2033H

• Use of the RE32 in-circuit emulator

The LC72E32's EPROM can be written using the RE32 in-circuit emulator. This requires the use of a specialpurpose adapter, the LC72E32 Adapter for RE32. Use the PGOTP command as the writing technique.

2. Special-purpose EPROM writing adapters

As mentioned above, there are two EPROM writing techniques, each of which requires the use of the appropriate adapter.



Note: The external dimensions of these two adapters are essentially identical.

```
General-purpose EPROM programmer adapter:

Product name: LC72E32 Adapter for EPROM Programmer

Product code: NDK-DC-001-A

RE32 in-circuit emulator adapter:

Product name: LC72E32 Adapter for RE32

Product code: NDK-DC-003-A
```

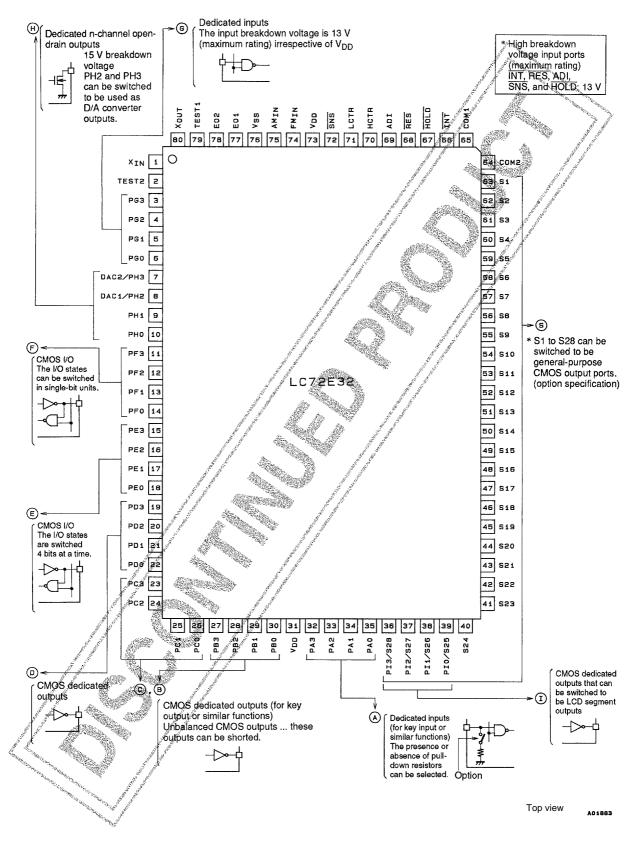
• Erasure

Use a general-purpose EPROM eraser to erase written data.

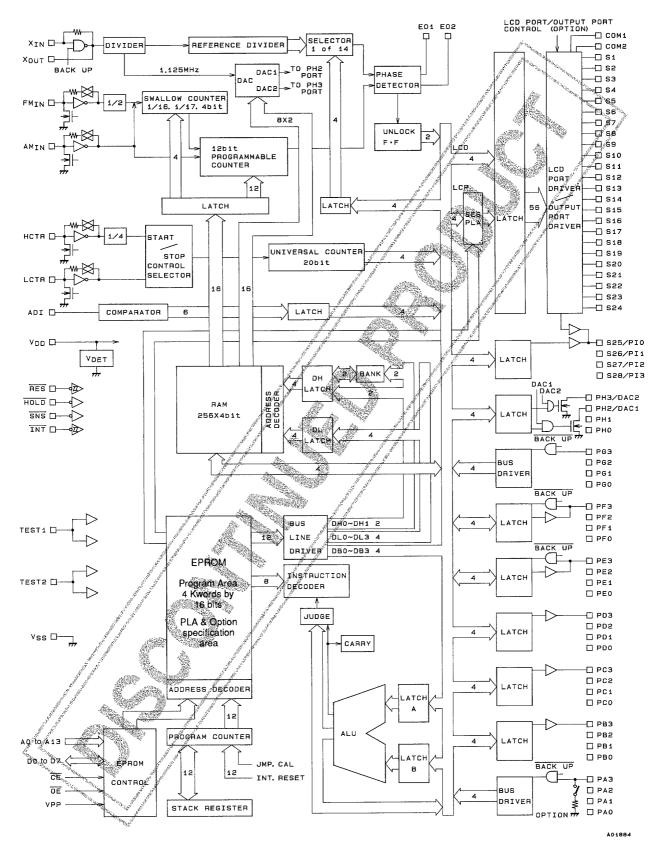
• Light Seal 🔬

The LC72E32 includes UVEPROM, i.e., ultraviolet erasable EPROM. When actually using an LC72E32, its window should be covered with UV-opaque tape.

Pin Assignment



Block Diagram



LC72E32 Instruction Table

Abbreviations:

ADDR: Program memory address [12 bits]

- b: Borrow
- B: Bank number [2 bits]
- C: Carry
- DH: Data memory address high (row address) [2 bits]
- DL: Data memory address low (column address) [4 bits]
- I: Immediate data [4 bits]
- M: Data memory address
- N: Bit position [4 bits]
- Pn: Port number [4 bits]
- r: General register (one of the locations 00 to 0FH in bank 0)
- Rn: Register number [4 bits]
- (): Contents of register or memory
- ()n: Contents of bit N of register or memory

						<u>20 - 10</u>	50	<u> 1998</u>	47		A.F. Jak	r.		
p		Ope	rand	- <i>*</i>		20		, <u>, , , , , , , , , , , , , , , , , , </u>		and a second	M	achine	code	
Instruction Group	Mnemonic	1st	2nd	Function	Operation	D 15	14	13	12	Ĵ.	10	98	7654	3 2 1 D0
	AD	r	М	Add M to r	$r \leftarrow (r) + (M)$	0	1	0	Ø	0	0	DH	DL	Rn
	ADS	r	м	Add M to r, then skip if carry	r ← (r) ≠ (M) skip if carry	0	1	,0	0	0	1	DH	DL	Rn
suc	AC	r	М	Add M to r with carry	, r ← (r) + (M) + C	0.**	f	0	0	1	0	DH	DL	Rn
Addition instructions	ACS	r	м	Add M to r with carry, then skip if carry	,r ← (r) + (M) + C skip if carry	O	1	0	0	1	1	DH	DL	Rn
D in	AI	М	I	Add I to M	$M \leftarrow (M) + I$	0	1	0	1	0	0	DH	DL	I
Additic	AIS	М	I	Add I to M, then skip if carry	$M \leftarrow (M) + 1$ skip if carry	0	1	0	1	0	1	DH	DL	I
	AIC	М	I	Add I to M with carry	M ← (M) + I + C	0	1	0	1	1	0	DH	DL	I
	AICS	М	I	Add I to M with carry, then skip if carry	M ← (M) + I + C skip it carry	0	1	0	1	1	1	DH	DL	I
	SU	r	М	Subtract M from r	n (r) − (M)	0	1	1	0	0	0	DH	DL	Rn
	SUS	r	М	Subtract M from r then skip if borrow	$r \leftarrow (r) - (M)^{r}$ skip if þörröw	0	1	1	0	0	1	DH	DL	Rn
s	SB	r	М	Subtract M from t with borrow	$r \leftarrow (r) - (M) - b$	0	1	1	0	1	0	DH	DL	Rn
Subtraction instructions	SBS	r	M	Subtract M from r with borrow then skip if borrow	r.⊭– (r) – (M) – b Skip if borrow	0	1	1	0	1	1	DH	DL	Rn
tion	SI	M	ĵ I	Subtract I from M	$M \gets (M) - I$	0	1	1	1	0	0	DH	DL	I
ubtract	SIS	M	1	Subtract I from M, then skip if borrow	M ← (M) – I skip if borrow	0	1	1	1	0	1	DH	DL	I
	SIB stand	Μ.		Subtract I from M with berrow	$M \gets (M) - I - b$	0	1	1	1	1	0	DH	DL	I
	SIBS	M		Subtract I from M with borrow, then skip if borrow	$M \leftarrow (M) - I - b$ skip if borrow	0	1	1	1	1	1	DH	DL	I
Suc	SEQ	r	м	Skip#f requals M	r – M skip if zero	0	0	0	0	0	1	DH	DL	Rn
Comparison instructions.	SGE	r Service Service	M	Skip if r is greater than or equal to M	r - M skip if not borrow $(r) \ge (M)$	0	0	0	0	1	1	DH	DL	Rn
parison	SEQI	M	and the second	Skip if M equal to I	M – I skip if zero	0	0	1	1	0	1	DH	DL	I
Com	SGEI	М	Ι	Skip if M is greater than or equal to I		0	0	1	1	1	1	DH	DL	I

ion		Ope	rand								м	achine	code		
Instruction Group	Mnemonic	1st	2nd	Function	Operation	D15	514	13	12	11		9 8	7 6 5 4	3 2 1	D0
	AND	М	I	AND I with M	$M \gets (M) \land I$	0	0	1	1	0	0	DH	DL	1	
Logical operation instructions	OR	М	I	OR I with M	M ← (M) ∨ I	0	0	1	1		0	DH	DL		
Logica	EXL	r	М	Exclusive OR M with r	$r \leftarrow (r) \oplus (M)$	0	0	1	0	0	0	DH	^{SQ} PL	Rn	
	LD	r	М	Load M to r	$r \gets (M)$	1	0	0	* ^{c*} 0	0	Ó	DH	DL 🖉	Rn	
	ST	М	r	Store r to M	$M \gets (r)$	1	Ø	0	0	0	1	DH	DL	Rn	
ctions	MVRD	r	М	Move M to destination M referring to r in the same row	[DH, Rn] ← (M)	and the second	0	0	Ó	1	0	рн	Dk	Rn	
Transfer instructions	MVRS	Μ	r	Move source M referring to r to M in the same row	M ← [DH, Rn]	1	0	0 0	0		1	DH	DL	Rn	
Trans	MVSR	M1	M2	Move M to M in the same row	[DH, DL1] ← [DH, DL2]			ò		0	0	ĎН	DL1	DL2	
	MVI	М	Ι	Move I to M	M ← I	2.1	0	<u>0</u> .	1	0	1	DH	DL	I	
	PLL	М	r	Load M to PLL registers	PLL r ← PLL DATA		0	^{//} 0	1	1	0	DH	DL	Rn	
t ttions	ТМТ	М	N	Test M bits, then skip if all bits specified are true	if M (N),≕ all 1s, then skip	1	0	A. A	2 ⁵⁰	0	1	DH	DL	N	
Bit test instructions	TMF	Μ	Ν	Test M bits, then skip if all bits specified are false	if M (N) = all 0s; then skip	1	03	12		1	1	DH	DL	N	
ne	JMP	AD	DR	Jump to the address	PC ← ADDR	Â	0	1	1			A	DDR (12 bits)	
Jump and subroutine call instructions	CAL	AD	DR	Call subroutine	PC ← ADDR Stack ← (PC) + 1	1	1	0	0			Д	DDR (12 bits)	
np a Linst	RT			Return from subroutine	P© ← Stack	1	1	0	1	0	1	0 0	0 0 0 0	0 0 0	0
Jur cal	RTI			Return from interrupt	PC — Stack	1	1	0	1	0	1	0 1	0 0 0 0	0 0 0	0
F/F test instructions	TTM	Ν		Test timer F/F then skip if it has not been set	if timer F/F = 0, then skip	1	1	0	1	0	1	1 0	0 0 0 0	N	
F/F test instructio	TUL	Ν		Test unløck F/F then skip if it has nøt been set	if UL F/F ≠ 0, then skip	1	1	0	1	0	1	1 1	0 0 0 0	N	
ctions	SS	Ν	A. A	Set status register	(Status register 1) N ← 1	1	1	0	1	1	1	0 0	0 0 0 0	N	
Status register instructions	RS	N	all contracts	Reset status register	(Status register 1) $N \leftarrow 0$	1	1	0	1	1	1	0 1	0000	N	
s registe	TST	N. S.	j Kirist	Test status register true	if (Status register 2) N = all 1s, then skip	1	1	0	1	1	1	1 0	0000	N	
	TSF	N		Test status register false	if (Status register 2) N = all 0s, then skip	1	1	0	1	1	1	1 1	0 0 0 0	N	
Bank switching	BANK	В		Select bank	$BANK \gets B$	1	1	0	1	0	0	В	0000	000	0
A. S.			29 												

ction		Ope	rand			Machine code
Instruction Group	Mnemonic	1st	2nd	Function	Operation	D15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 D0
	LCD	М	Ι	Output segment pattern to LCD digit direct	$LCD\;(DIGIT) \gets M$	1 1 1 0 0 0 DH DL DIGIT
	LCP	М	I	Output segment pattern to LCD digit through PLA	$LCD\;(DIGIT) \gets PLA \gets M$	1 1 1 0 0 1 DH DL DIGIT
dnc	IN	М	Р	Input port data to M	$M \gets (Port\ (P))$	1 1 1 0 1 0 DH DL P
Ö	OUT	М	Р	Output contents of M to port	$(Port (P)) \leftarrow M$	1 1 1 9 1 1 DL P
stion	SPB	Р	N	Set port bits	(Port (P)) N ← 1	1 1 1 1 1 0 0 0 0 P / N
struc	RPB	Р	N	Reset port bits	(Port (P)) N ← 0	1 1 1 1 0 1 0 1 P N
I/O instruction Group	ТРТ	Ρ	N	Test port bits, then skip if all bits specified are true	if (Port (P)) N = all 1s, then skip	1 1 1 1 0 0 0 P N
	TPF	Ρ	N	Test port bits, then skip if all bits specified are false	if (Port (P)) N = all 0s, then skip	1 1 1 1 1 1 1 P N
l counter ns	UCS	I		Set I to UCCW1	UCCW1 ← I	
Universal counter instructions	UCC	I		Set I to UCCW2		
sr	FPC	Ν		F port I/O control	FPC latch – N	0 0 0 1 0 0 0 0 0 0 0 0 N
Other instructions	CKSTP			Clock stop	Stop clock if HOLD = 0	0 0 0 1 0 0 1 0 0 0 0 0 0 0 0 0
Other instruc	DAC	Ι		Load M to D/A registers	DAreg ← DAC DATA	0_000000100000
⊇. Ó	NOP			No operation		Ø 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0

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